

ABSTRACT

The present invention addresses the problem of providing a technology of transferring a paste to an electronic component. As a means for solving the problem, a paste (11) is provided on a table (10), and an electronic component (13) is provided on a sheet (14). The table (10) and the sheet (14) are provided by having a space therebetween such that the paste (11) and the electronic component (13) are facing each other. The sheet (14) is warped so that the paste (11) and the electronic component (13) are close to each other, and the electronic component (13) is pressed to the paste (11). The paste (11) is adhered to the electronic component (13) by separating the electronic component (13) from the paste (11) that has been provided on the table (10).